ABSTRACT OF THE DISCLOSURE

THERMOSETTING RESIN SHEET FOR SEALING ELECTRONIC COMPONENT, RESIN-SEALED TYPE SEMICONDUCTOR DEVICE, AND METHOD FOR PRODUCING RESIN-SEALED TYPE SEMICONDUCTOR DEVICE

A thermosetting resin sheet for sealing an electronic component, that is excellent in adhesiveness, onto the electric component; a resin-sealed type semiconductor device high in reliability; and a method for producing the device are provided. The present invention relates to a thermosetting resin sheet for sealing an electronic component, comprising one or more resin components, one of the components being allowable to be a thermoplastic resin, and having a content by percentage of the thermoplastic resin of 30% or less by weight of all of the entire resin components.

Fig. 1

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